

ISSUE CLASSIFICATION	
Class	Subclass


$$\frac{J_{C1}}{J_{C23}}$$

PATENT DATE

SCANNED

Q.A

APPLICATION NO. 09/586525	CONT/PRIOR	CLASS 257	SUBCLASS 778	ART UNIT 2811	EXAMINER Wodan
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TITLE

Substrate structure of flip chip package

PTO-2040
12/89[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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